

Appl. No. 10/604,611
Amdt. dated April 08, 2005
Reply to Office action of March 10, 2005

Amendments to the Claims:

1. (Original) A probe tip for flip-chip packaging process, the probe tip comprising:
a needle body; and
5 a stop cylinder having a recess for accommodating the needle body therein, the
needle body being electrically connected to the stop cylinder via a resilient conductive
material;
wherein the stop cylinder has an annual flat bottom surrounding the needle body for
pressing a protruding probe mark on a metal pad scratched by the needle body.
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2. (Original) The probe tip for flip-chip packaging process of claim 1 wherein the metal
pad is made of aluminum or copper and is formed on a chip.
3. (Original) The probe tip for flip-chip packaging process of claim 1 wherein the
15 needle body protrudes from the bottom of the stop cylinder by at least 1 micron.
4. (Original) The probe tip for flip-chip packaging process of claim 1 wherein the
resilient conductive material is conductive glue.
- 20 5. (Original) The probe tip for flip-chip packaging process of claimed wherein the
annual flat bottom has a width of about 20 microns to 30 microns.
- 6-13 (Canceled)
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